

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TSUKASA SEKINO	02/26/2016
HIROSHI YAMASHITA	02/26/2016
DAISUKE OKAMOTO	02/26/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	YAZAKI CORPORATION
<b>Street Address:</b>	4-28, MITA 1-CHOME, MINATO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	108-8333
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15067813
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	1451562.566US3
<b>NAME OF SUBMITTER:</b>	JAMES E. ARMSTRONG, IV
<b>SIGNATURE:</b>	/James E. Armstrong, IV/
<b>DATE SIGNED:</b>	03/11/2016
<b>Total Attachments: 3</b>	
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**ASSIGNMENT BY INVENTORS**

**THIS ASSIGNMENT**, made by **(1) Tsukasa SEKINO**,  
**(2) Hiroshi YAMASHITA and (3) Daisuke OKAMOTO** (hereinafter referred to as  
Assignors), residing at 1) 2) 3) c/o Yazaki Parts Co., Ltd., 206-1, Nunohikihara, Makinohara-  
shi, Shizuoka 421-0407, Japan;

**WHEREAS**, Assignors have invented certain new and useful improvements in  
POWER-SUPPLYING DEVICE AND ASSEMBLY METHOD OF  
POWER-SUPPLYING DEVICE

set forth in a Patent application for which an International Application was filed on

\_\_\_\_\_, PCT/JP \_\_\_\_\_, designating the United States; and

**WHEREAS**, Yazaki Corporation, a Corporation organized under and pursuant to  
the laws of Japan having its principal place of business at 4-28, Mita 1-chome, Minato-ku,  
Tokyo 108-8333, Japan (hereinafter referred to as Assignee), is desirous of acquiring the entire  
right, title and interest in and to said inventions and said Application for Letters Patent of the  
United States, and in and to any Letters Patent of the United States to be obtained therefore and  
thereon.

**NOW, THEREFORE**, for good and sufficient consideration, the receipt of which  
is hereby acknowledged, Assignors have sold, assigned, transferred and set over, and by these  
presents do sell, assign, transfer and set over, unto Assignee, its successors, legal  
representatives and assigns, the entire right, title and interest in and to the above-mentioned  
inventions and application for Letters Patent, and in and to any and all direct and indirect  
divisions, continuations and continuations-in-part of said application, and any and all Letters  
Patent in the United States and all foreign countries which may be granted therefor and thereon,  
and reissues, reexaminations and extensions of said Letters Patent, and all rights under the  
International Convention for the Protection of Industrial Property, the same to be held and  
enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal  
representatives and assigns, to the full end of the term or terms for which Letters Patent may be  
granted and/or extended, as fully and entirely as the same would have been held and enjoyed by  
Assignors, had this sale and assignment not been made.

**AND** for the same consideration, Assignors hereby represent and warrant to Assignee, its successors, legal representatives and assigns, that, at the time of execution and delivery of these presents, except for any rights, titles and/or interests that have arisen to Assignee under law or that have already been transferred to Assignee, Assignors are the sole and lawful owners of the entire right, title and interest in and to the said inventions and application for Letters Patent above-mentioned, and that the same are unencumbered and that Assignors have good and full right and lawful authority to sell and convey the same in the manner herein set forth.

**AND** for the same consideration, Assignors hereby covenant and agree to and with Assignee, its successors, legal representatives and assigns that: Assignors will sign all papers and documents, take all lawful oaths and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Letters Patent and applications for Letters Patent for said inventions, without charge to Assignee, its successors, legal representatives and assigns, whenever counsel of Assignee, or counsel of its successors, legal representatives and assigns, shall advise; that any proceeding in connection with said inventions, or said Patent application for Letters Patent, or any proceeding in connection with any Letters Patent or applications for Letters Patent for said inventions in any country, including but not limited to interference proceedings, is lawful and desirable; and, that any division, continuation or continuation-in-part of any application for Letters Patent, or any reissue, reexamination or extension of any Letters Patent, to be obtained thereon, is lawful and desirable.

**AND** Assignors hereby request the Commissioner of Patent and Trademarks to issue said Letters Patent of the United States to Assignee, as Assignee of said inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns.

**AND** Assignors hereby grant the following individuals the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document:

LOCKE LORD LLP

All practitioners at Customer Number 21874

AND Assignors acknowledge an obligation of assignment of this invention to Assignee at the time the invention was made.

Date: February 26, 2016      Signature: *Tsukasa Sekino*  
Tsukasa SEKINO

Date: February 26, 2016      Signature: *Hiroshi Yamashita*  
Hiroshi YAMASHITA

Date: February 26, 2016      Signature: *Daisuke Okamoto*  
Daisuke OKAMOTO